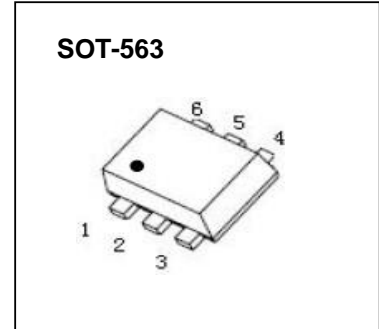


Plastic-Encapsulate MOSFETs

N Channel + P Channel Power MOSFET

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
60 V	5Ω@10V	0.34A
	5.3Ω@4.5V	
-50V	8Ω@-10V	-0.18A
	10Ω@-5V	



DESCRIPTION

This N Channel + P Channel MOSFET has been designed using advanced power trench process to optimize the $R_{DS(ON)}$.

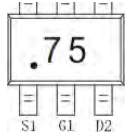
FEATURE

- High-Side Switching
- Low Threshold
- Fast Switching Speed

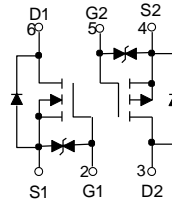
APPLICATION

- Drivers:Relays, Solenoids, Memories
- Battery Operated Systems
- Power Supply Converter Circuits
- Load/Power Switching Cell Phones, Pagers

MARKING: 75



Equivalent Circuit



MAXIMUM RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Value	Unit
N-Channel MOSFET			
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	±20	V
I_D	Drain Current -Continuous	0.34	A
I_{DM}	Drain Current - Pulsed(Note1)	1.36	A
P- Channel MOSFET			
V_{DS}	Drain-Source Voltage	-50	V
V_{GS}	Gate-Source Voltage	±20	V
I_D	Drain Current -Continuous	-0.18	A
I_{DM}	Drain Current – Pulsed (Note1)	-0.7	A
Power Dissipation, Temperature and Thermal Resistance			
P_D	Power Dissipation	0.15	W
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient (Note2)	833	°C/W
T_j	Junction Temperature	150	°C
T_{stg}	Storage Temperature	-55~+150	°C
T_L	Lead Temperature	260	°C



FTK1029NP

MOSFET ELECTRICAL CHARACTERISTICS

T_a=25 °C unless otherwise specified

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
N- Channel MOSFET						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	60			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =48V, V _{GS} =0V			1	μA
Gate-body leakage current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V			±10	μA
		V _{GS} =±10V, V _{DS} =0V			±200	nA
		V _{GS} =±5V, V _{DS} =0V			±100	nA
Gate threshold voltage (note 3)	V _{GS(th)}	V _{DS} =V _{GS} , I _D =1mA	1	1.3	2.5	V
Drain-source on-resistance (note 3)	R _{DS(on)}	V _{GS} =4.5V, I _D =0.2A		1.1	5.3	Ω
		V _{GS} =10V, I _D =0.5A		0.9	5	Ω
Diode forward voltage	V _{SD}	I _S =0.3A, V _{GS} =0V			1.5	V
DYNAMIC PARAMETERS (note 4)						
Input Capacitance	C _{iss}	V _{DS} =10V, V _{GS} =0V, f=1MHz			40	pF
Output Capacitance	C _{oss}				30	pF
Reverse Transfer Capacitance	C _{rss}				10	pF
SWITCHING PARAMETERS (note 4)						
Turn-on delay time	t _{d(on)}	V _{GS} =10V, V _{DD} =50V,			10	ns
Turn-off delay time	t _{d(off)}	R _L =250Ω, R _{GEN} =50Ω,			15	ns
Reverse recovery time	t _{rr}	I _S =300mA;		30		ns
Recovered charge	Q _r	dI _S /dt=-100A/s; V _{GS} =0V; V _R =25V		30		nC
P- Channel MOSFET						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =-250μA	-50			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =-50V, V _{GS} =0V			-15	μA
		V _{DS} =-25V, V _{GS} =0V			-0.1	μA
Gate-body leakage current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V			±10	μA
Gate threshold voltage (note 3)	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-0.9	-1.62	-2	V
Drain-source on-resistance (note 3)	R _{DS(on)}	V _{GS} =-5V, I _D =-0.1A		5.5	10	Ω
		V _{GS} =-10V, I _D =-0.1A		4.1	8	Ω
Forward transconductance (note 3)	g _{FS}	V _{DS} =-25V, I _D =-0.1A	0.05			S
DYNAMIC CHARACTERISTICS (note 4)						
Input capacitance	C _{iss}	V _{DS} =-5V, V _{GS} =0V, f=1MHz		30		pF
Output capacitance	C _{oss}			10		pF
Reverse transfer capacitance	C _{rss}			5		pF
SWITCHING CHARACTERISTICS (note 4)						
Turn-on delay time	t _{d(on)}	V _{DD} =-15V, R _L =50Ω, I _D =-2.5A		2.5		ns
Turn-on rise time	t _r			1		ns
Turn-off delay time	t _{d(off)}			16		ns
Turn-off fall time	t _f			8		ns
SOURCE – DRAIN DIODE CHARACTERISTICS (note 4)						
Continuous Current	I _S	I _S =-0.13A, V _{GS} =0V			-0.18	A
Pulsed Current	I _{SM}				-0.7	A
Diode forward voltage (note 3)	V _{DS}				-2.2	V

- Note:**
- 1、 Surface mounted on FR-4 board using minimum pad size, 1oz copper
 - 2、 Repetitive Rating: Pulse width limited by maximum junction temperature.
 - 3、 Pulse test: pulse width ≤300μs, duty cycle ≤2%
 - 4、 These parameters have no way to verify.

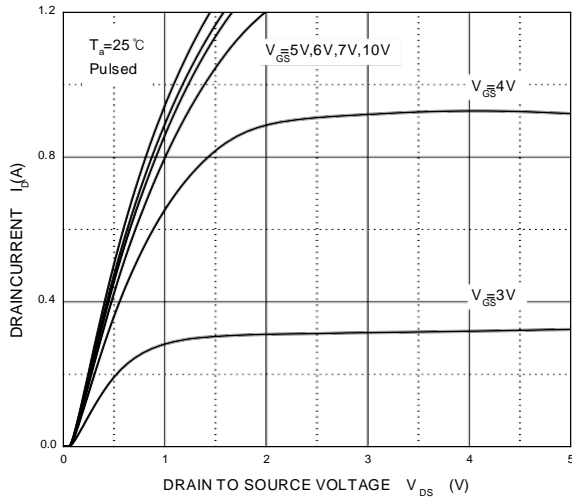


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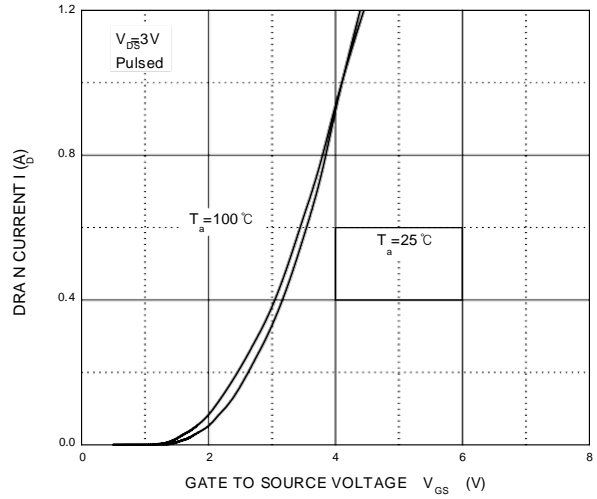
Typical Characteristics

N-Channel MOS

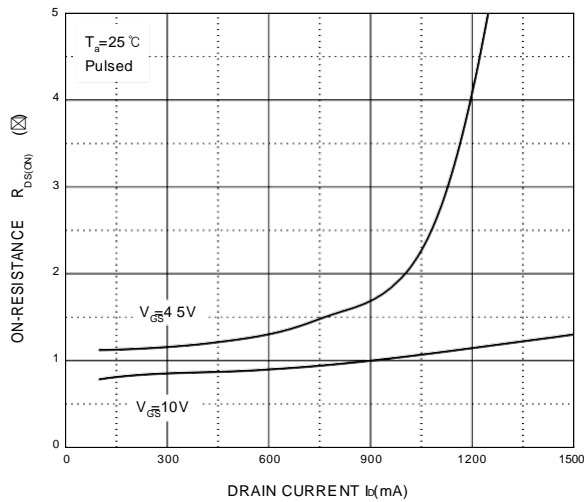
Output Characteristics



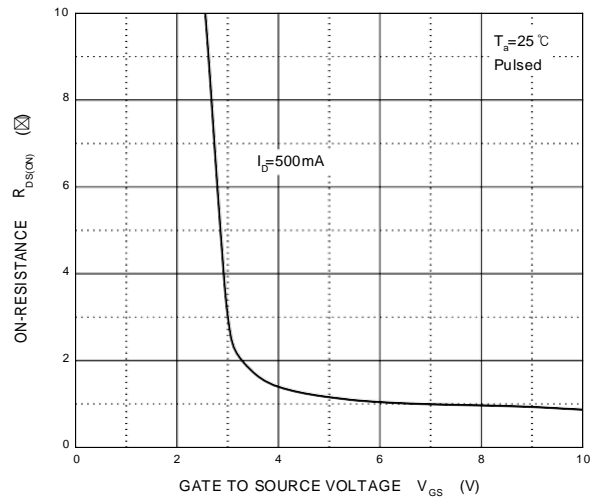
Transfer Characteristics



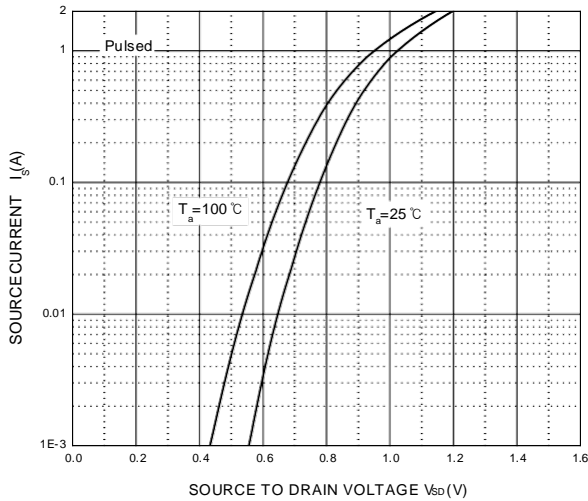
$R_{DS(ON)}$ — I_D



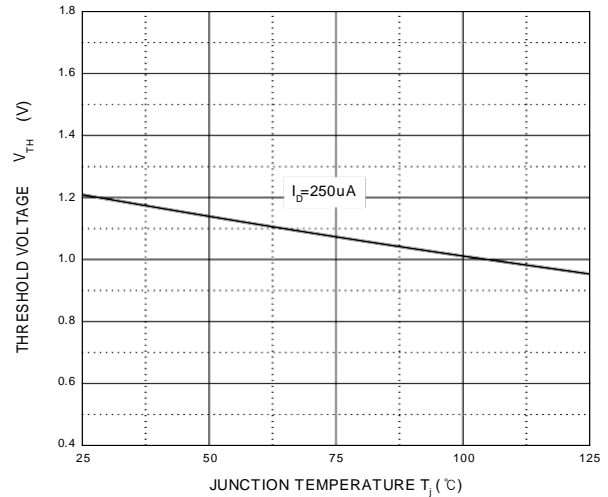
$R_{DS(ON)}$ — V_{GS}



I_S — V_{SD}



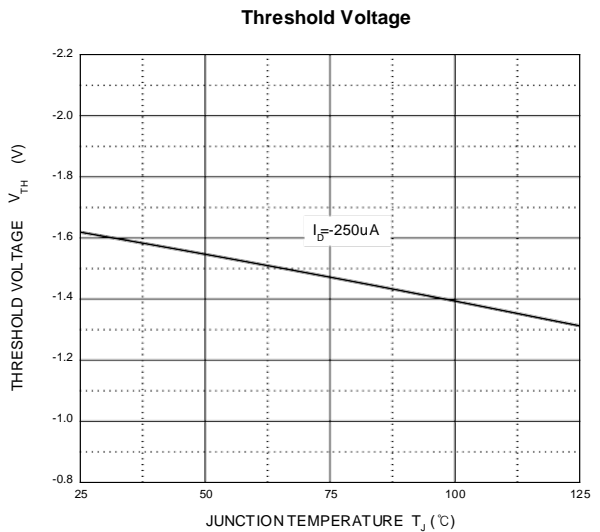
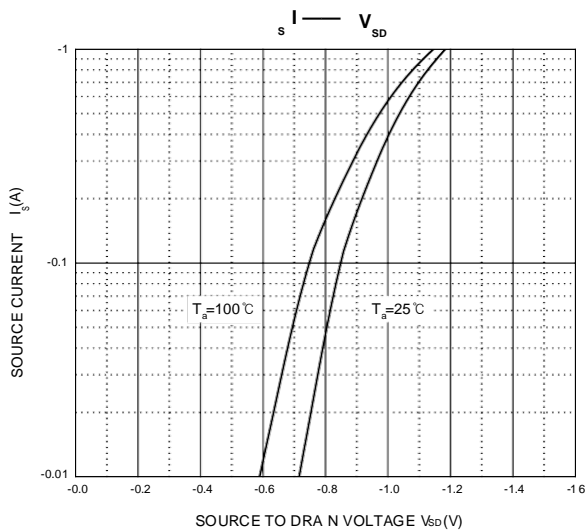
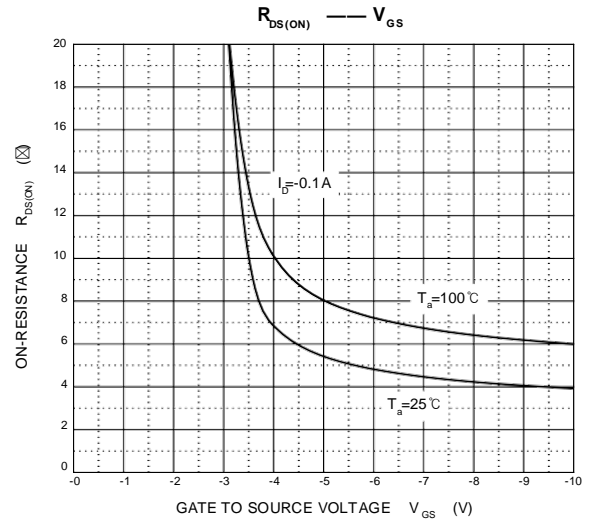
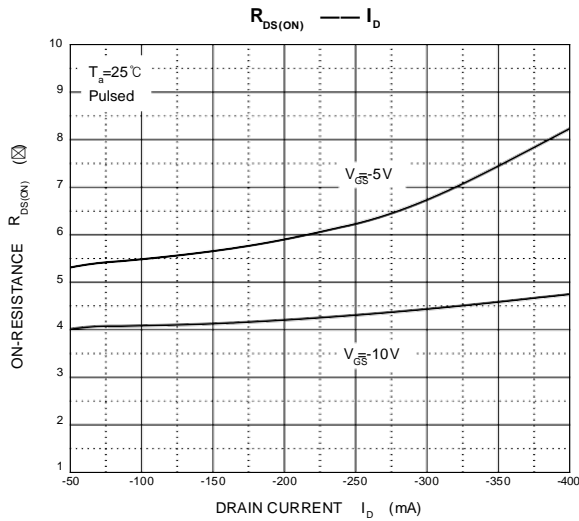
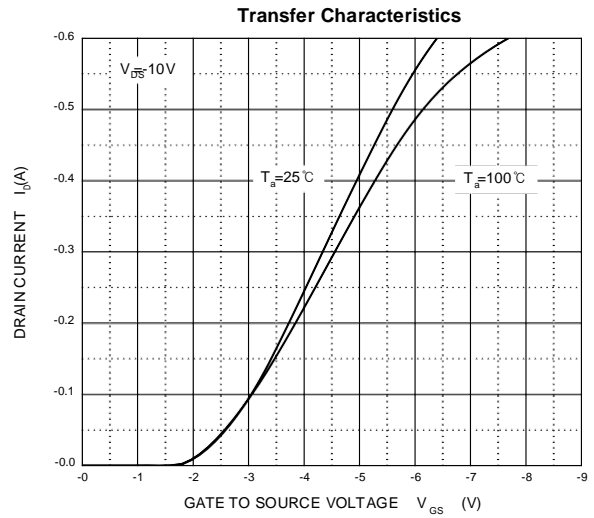
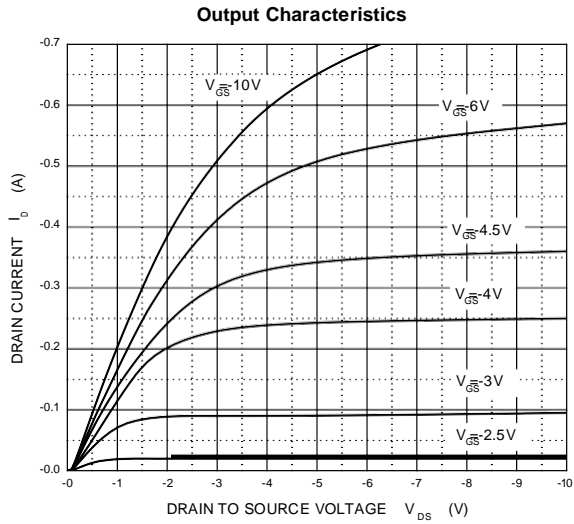
Threshold Voltage





FTK1029NP

Typical Characteristics P-Channel MOS





FTK1029NP

ne Dimensions

Symbol	Dimension in Millimeters	
	Min	Max
A	0.90	1.00
A1	0.010	0.100
B	1.20	1.40
bp	0.25	0.45
C	0.09	0.15
D	2.00	2.20
E	1.15	1.35
HE	2.15	2.55
Lp	0.25	0.46
θ	0°	6°